LNJ624C4CRA

Hight Bright Surface Mounting Chip LED

3528 (PLCC2) Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	PD	80	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	70	mA	
Reverse voltage	V _R	5	V	
Operating ambient temperature	T _{opr}	-40 to +100	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Lighting Color

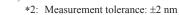
• Pure Green

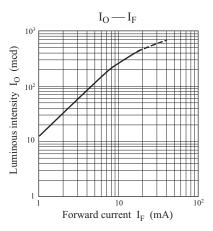
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

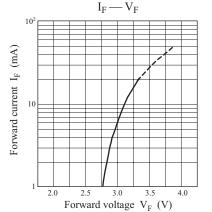
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *1	Io	$I_F = 10 \text{ mA}$	140	290	380	mcd
Reverse current	I _R	$V_R = 5 V$			100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$		3.2	3.9	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 10 \text{ mA}$		520		nm
Dominant emission wavelength *2	λ _d	$I_F = 10 \text{ mA}$	523	530	540	nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm

Note) *1: Measurement tolerance: ±15%





Relative luminous intensity $-\lambda_P$



Directive characteristics

50

60

70

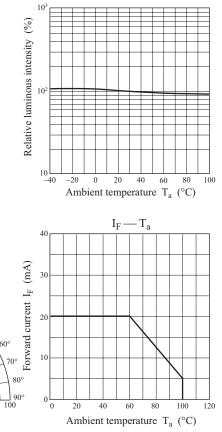
100

80

90° 650

 $-V_F$

Relative luminous intensity — T_a



450

500

Peak emission wavelength λ_P (nm)

550

600

100

80

60

40

20

0 400

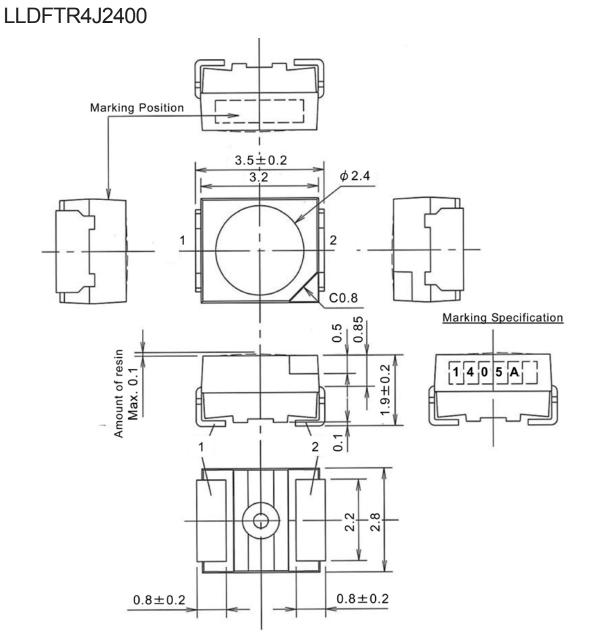
Relative luminous intensity (%)

Relative luminous intensity (%)

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Panasonic

Package (Unit: mm)



• Pin name

1: Anode

2: Cathode

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